

Sub C1

--32. A polishing pad assembly for polishing a semiconductor wafer comprising:
a belt forming a closed loop; and
at least one polishing pad mounted on the belt.--

--33. The polishing pad assembly of *Claim 32* in which said belt is formed of metal.—

Sub C2

--34. A polishing pad assembly for polishing a semiconductor wafer comprising:
a first roller;
at least one additional roller;
a belt forming a closed loop, which belt is mounted on said first roller and said at least one additional roller;
at least one polishing pad mounted to said belt; and
a drive system coupled to at least said first roller to rotate said first roller and to cause said belt and said polishing pad to move in a path.--

--35. The polishing pad assembly of *Claim 34* in which said belt is formed of metal.—

REMARKS

New Claims 32-35 correspond to Claims 32-35 as added by amendment in Application Serial No. 08/287,658 prior to the restriction requirement in that application.

Respectfully submitted,

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